

## EAST Search History

## EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5207	(438/14,18,108,763).CCLS.	USPAT; USOCR	OR	OFF	2010/08/28 14:53
L2	1004	L1 and (sputtering or ion adj milling)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/08/28 14:53
L3	229	L2 and (semiconductor and cleaning)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/08/28 14:53
L4	156	L3 and @ad< "20040225"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/08/28 14:53
L5	65	L4 and (argon or Ar or helium or He or neon or Ne)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/08/28 14:53
L6	5207	(438/14,18,108,763).CCLS.	USPAT; USOCR	OR	OFF	2010/08/28 14:54
L7	1004	L6 and (sputtering or ion adj milling)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/08/28 14:54
L8	229	L7 and (semiconductor and cleaning)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/08/28 14:54

L9	1767	(semiconductor with (wafer or substrate) with (test\$3 or prob\$3)) and ((ion milling) or (sputter\$3 with etch\$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/08/28 14:54
L10	1088	L9 and @ad< "20040225"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2010/08/28 14:54
L11	157	L10 and (((ion milling) or (sputter etch\$3)) and (testing or probing or test or probe\$1) with wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/08/28 14:54

### EAST Search History (I nterference)

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**8/ 28/ 2010 2:55:47 PM**

**C:\ Documents and Settings\ bau\ My Documents\ EAST\ Workspaces\ Metallization\ Electrical Contacts\ 10786807 bumps made of gold and its cleaning using ion milling before probing.wsp**